Abstract

A method for packaging and testing a semiconductor die is provided. The method includes forming a temporary package for the die that has a size, shape and lead configuration that is the same as a conventional plastic or ceramic semiconductor package. The temporary package can be used for burn-in testing of the die using standard equipment. The die can then be removed from the package and certified as a known good die. In an illustrative embodiment the package is formed in a SOJ configuration. The package includes a base, an interconnect and a force applying mechanism. The package base can be formed of ceramic or plastic using a ceramic lamination process or a Cerdip formation process.

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